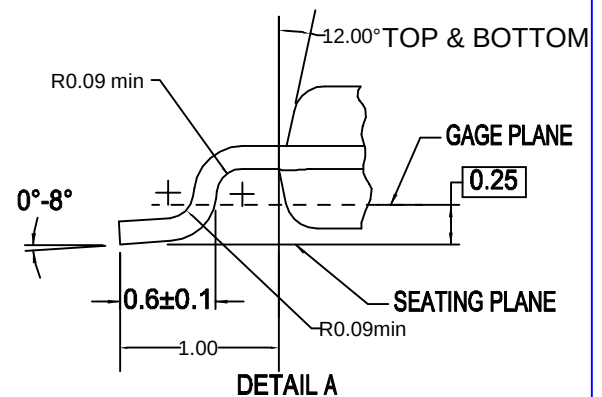
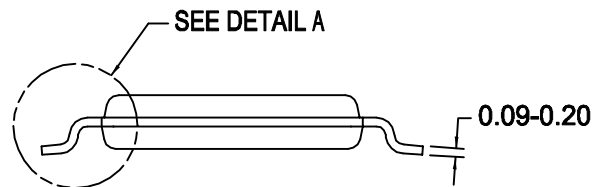
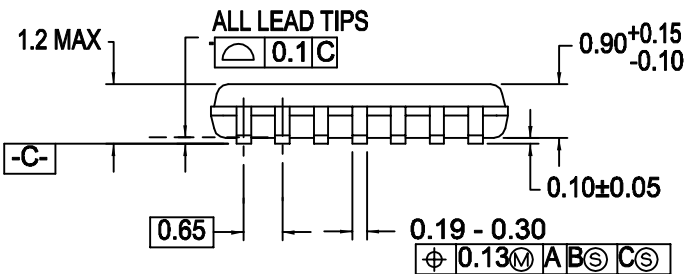
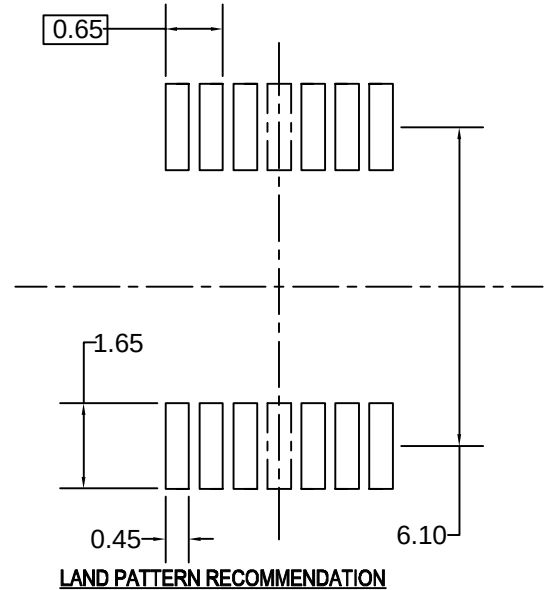
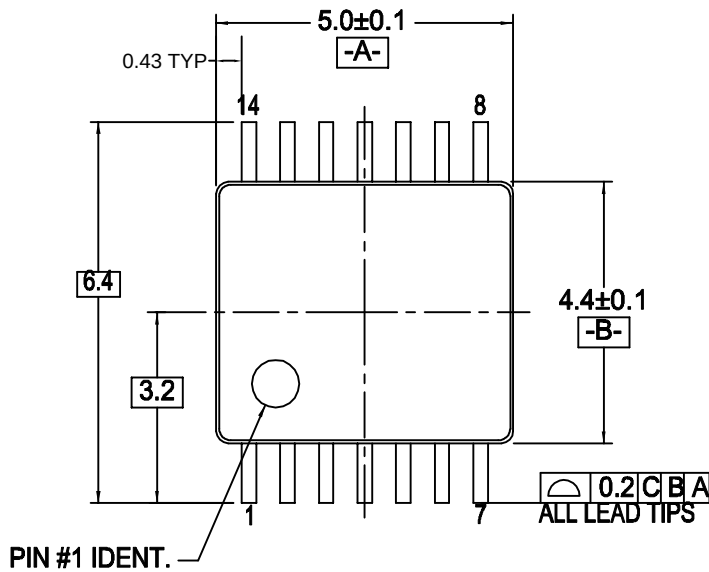


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APPD
C	REVISE & REDRAW ON PRO/E PER CURRENT STD; CORRECT DET CALLOUT FROM D TO A	11099	08/21/95	MS/
C1	CHANGE TO (FSMP) DRAWING		4-6-98	FEITAN
C2	ADDED NOTES SECTION, ADDED RADIUS DIMS, MOLDED BODY ANGLE DIMS, AND FILENAME		6-12-98	H.ALLEN
C3	CHANGED TITLE, ADDED TITLE		6-23-98	H.ALLEN
D	CHANGED REVISION LEVEL ONLY		11/12/04	H.ALLEN
6	UPDATED LAND PATTERN		9 JULY 07	L.HUEBENER



NOTES:

- CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6
- DIMENSIONS ARE IN MILLIMETERS
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- LANDPATTERN STANDARD: SOP65P640X110-14M
- DRAWING FILE NAME: MTC14REV6

APPROVALS		DATE	FAIRCHILD SEMICONDUCTOR	
DRAWN	L.HUEBENER	9 JULY 07	14LD, TSSOP, JEDEC MO-153, 4.4MM WIDE	
DFTG. CHK.	H.ALLEN	31 JULY 07		
ENGR. CHK.				
PROJECTION			SCALE	SIZE
INCH			N/A	C
MM			DRAWING NUMBER	REV
			MKT-MTC14	6
			DO NOT SCALE DRAWING	SHEET 1 of 1